

Abstract of the Disclosure

The invention of the present application provides a heat radiation structure of a semiconductor device, ~~comprising~~ and includes a substrate having, on a surface thereof, a first area on which the semiconductor device is mounted, and a second area which surrounds the first area, ~~and the area.~~ The semiconductor device ~~which~~ has a first surface and a second surface opposite to the first surface, and is formed with a plurality of terminals provided on the first ~~surface, wherein the~~ surface. The semiconductor device is mounted on the substrate in such a manner that the first surface is opposite to the surface of the ~~substrate, and wherein a~~ substrate. A first heat radiating film is formed on the second area of the substrate, and a second heat radiating film is formed on the second surface of the semiconductor device, with the second heat radiating film being spaced away apart from the first heat radiating film.